

# Numerical Study of Laminar Forced Convection Cooling of Circuit Board Mounted Heat Source Array

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## Abstract

This paper deals with the numerical study of optimal distribution of rectangular heat sources populated on a substrate board for electronic cooling. The simulations are performed for laminar forced convection conjugate heat transfer with vertical orientation of substrate board. The laminar forced convection - conjugate heat transfer simulations are carried out using COMSOL Multiphysics® with heat fluxes of 1500, 2000 and 2500 W/m<sup>2</sup> and at different air velocities and ambient temperatures. The simulations are carried out for various positions of heat sources so as to determine the optimal configuration. Out of the possible 168 million configurations, random sampling is performed to select three hundred possible random configurations to decide the optimal configuration.

## Reference

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- [2] S. O. Durgam et.al., “A numerical and experimental study of optimal distribution of discrete heat source array cooled by natural and forced convection”, In Proceedings of First TFESC-12696, Begell House, (2015).
- [3] Shankar Durgam et.al., " A Numerical and Experimental Study of Optimal Distribution of Rectangular Discrete Heat Sources Under Laminar Forced Convection", ihmtc-astfe conference, (2015)

# Figures used in the abstract

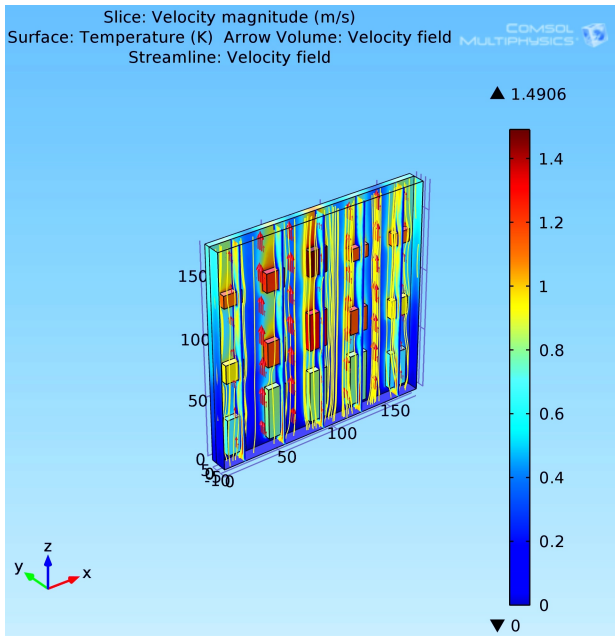


Figure 1: Velocity plot 1.

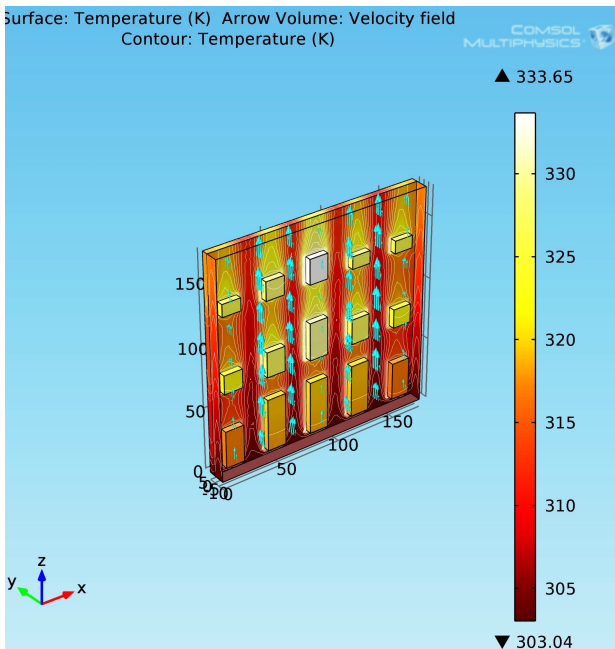
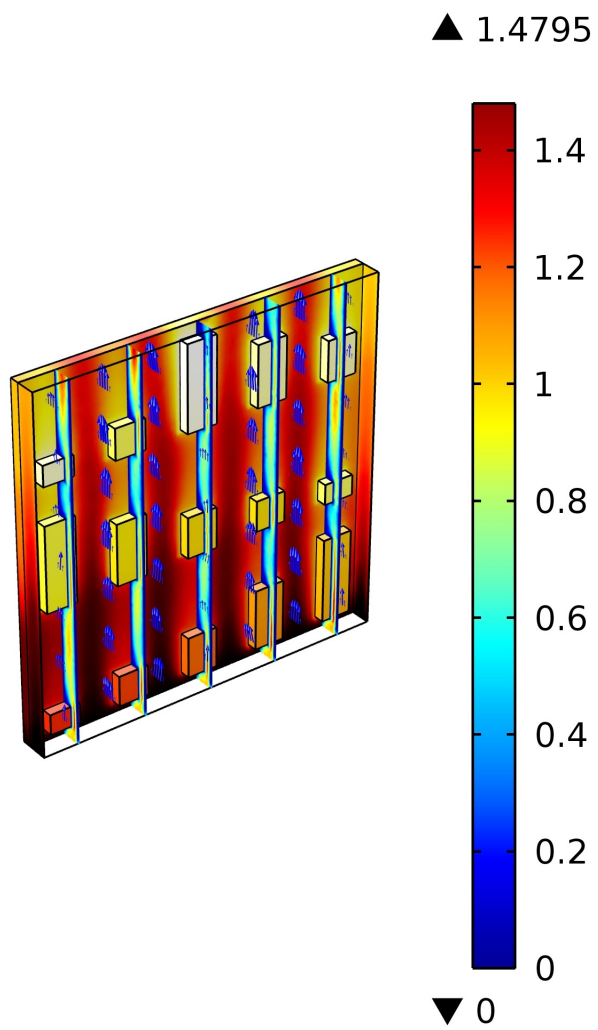
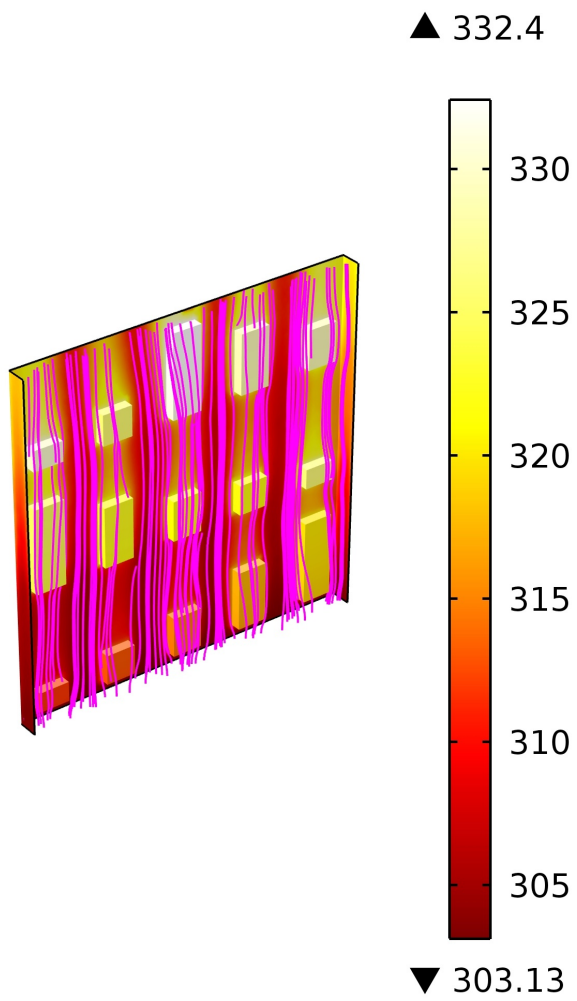


Figure 2: Temperature plot 1.



**Figure 3:** Velocity plot 2.



**Figure 4:** Temperature plot 2.